



SOD323

plastic, surface-mounted package; 2 leads; 1.3 mm pitch; 1.7 mm x 1.25 mm x 0.95 mm body

30 July 2019

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	SOD323
Package type industry code	SOD323
Package style descriptive code	SOD (small outline diode)
Package body material type	P (plastic)
JEITA package outline code	SC-76
Mounting method type	S (surface mount)
Issue date	16-03-2006
Manufacturer package code	SOD323

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.6	1.7	1.8	mm
package width	1.15	1.25	1.35	mm
seated height	0.8	0.95	1.1	mm
nominal pitch	-	1.3	-	mm
actual quantity of termination	-	2	-	



2 Package outline

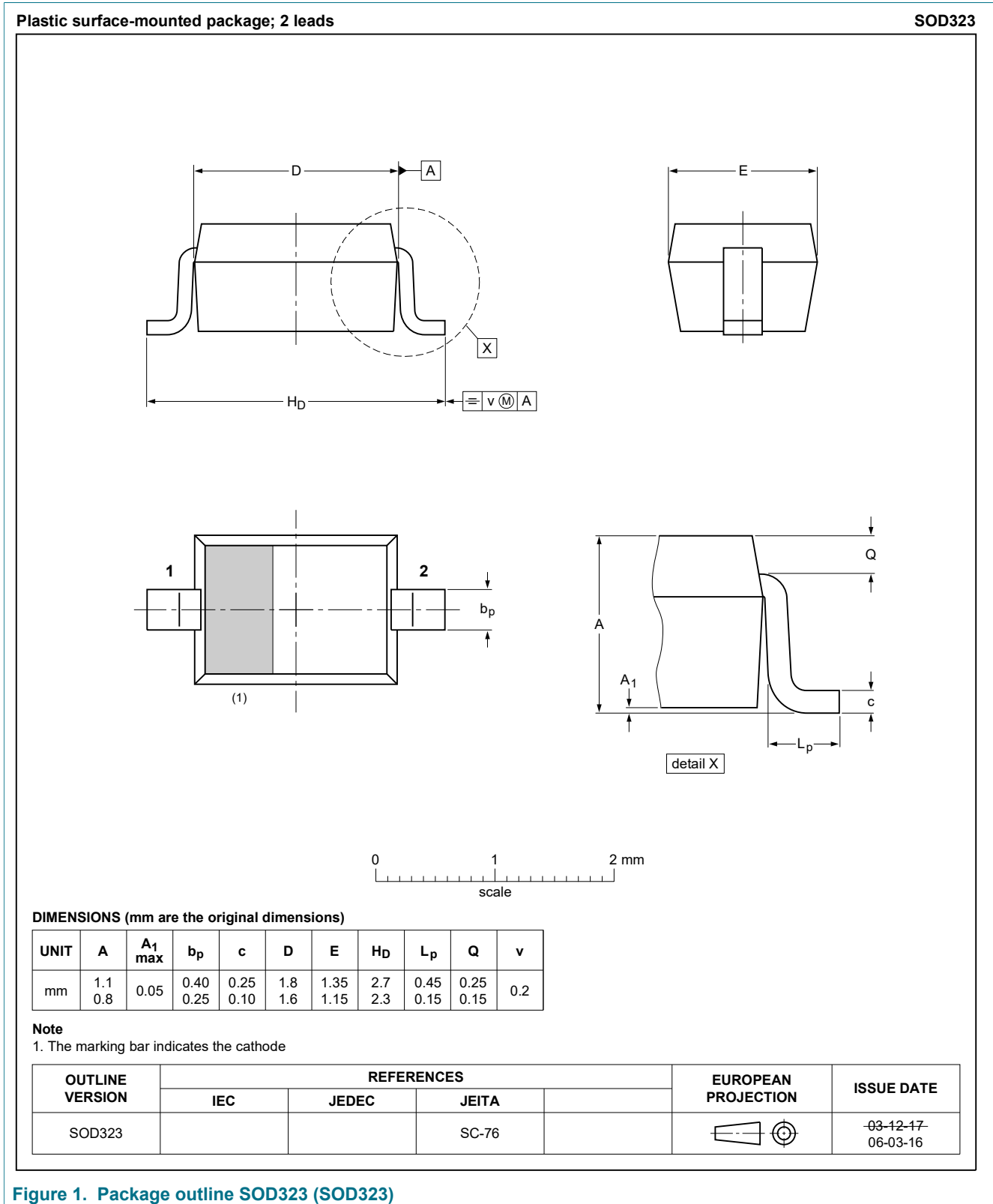
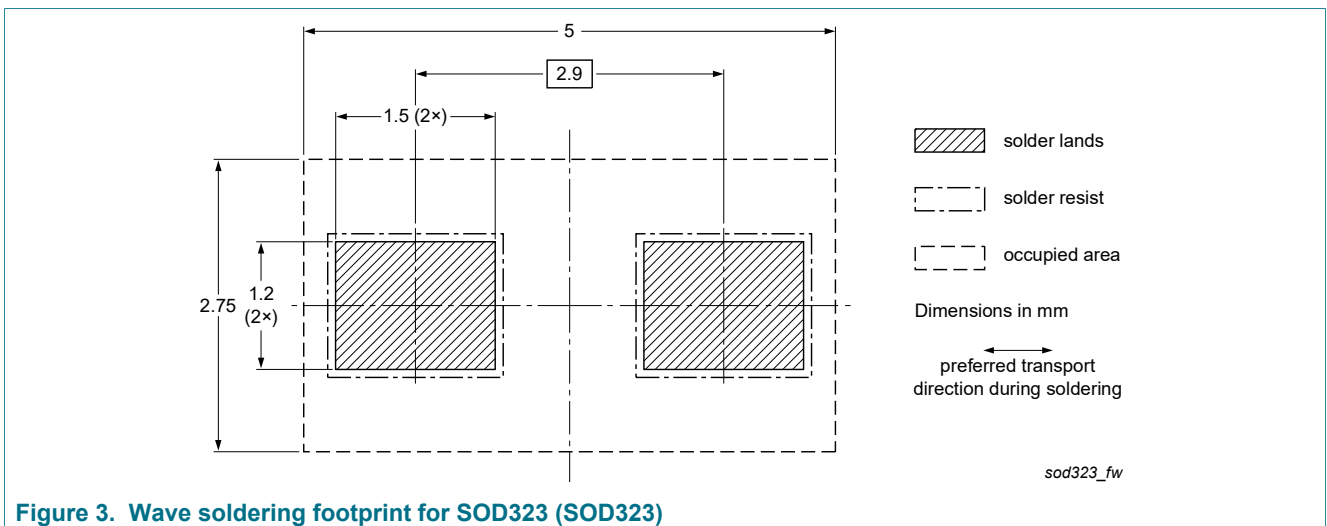
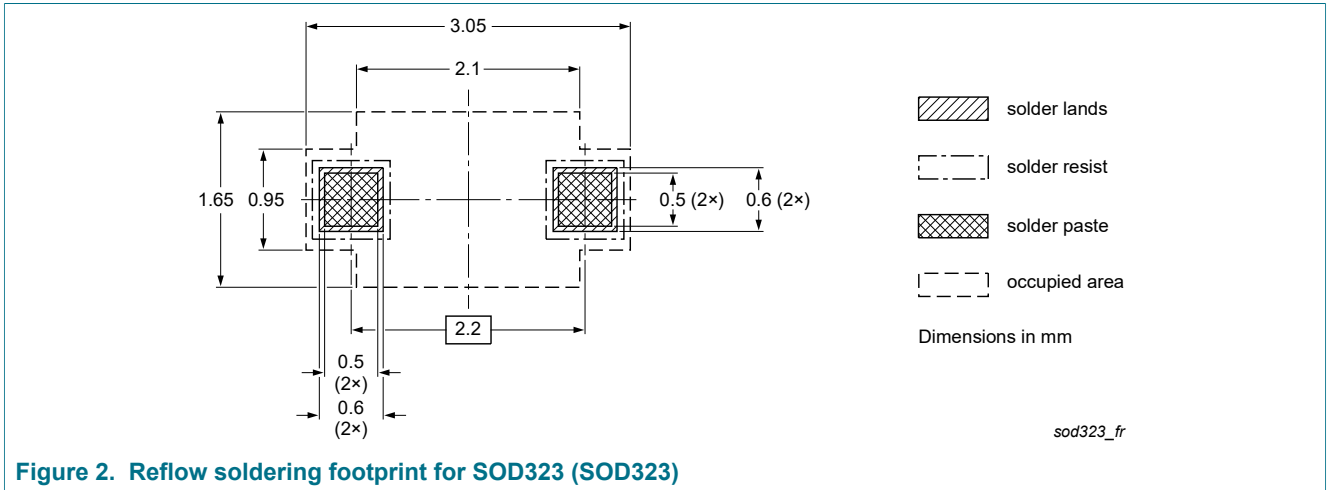


Figure 1. Package outline SOD323 (SOD323)

3 Soldering



4 Legal information

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